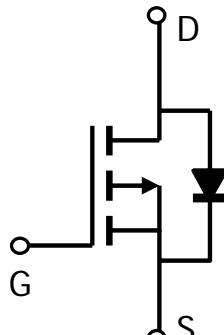


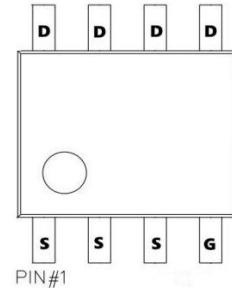
## General Description

The AO4485 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is suitable for use as a DC-DC converter application.



## Features

$V_{DS}$  (V) = -40V  
 $I_D$  = -10A  
 $R_{DS(ON)} < 15m\Omega$  ( $V_{GS} = -10V$ )  
 $R_{DS(ON)} < 20m\Omega$  ( $V_{GS} = -4.5V$ )



## Absolute Maximum Ratings $T_J=25^\circ C$ unless otherwise noted

Parameter		Symbol	10 Sec	Steady State	Units
Drain-Source Voltage		$V_{DS}$		-40	V
Gate-Source Voltage		$V_{GS}$		$\pm 20$	V
Continuous Drain Current <sup>A</sup>	$T_A=25^\circ C$	$I_D$	-12	-10	A
	$T_A=70^\circ C$		-9	-8	
Pulsed Drain Current <sup>B</sup>		$I_{DM}$		-120	
Avalanche Current <sup>G</sup>		$I_{AR}$		-28	
Repetitive avalanche energy $L=0.3mH$ <sup>G</sup>		$E_{AR}$		118	mJ
Power Dissipation <sup>A</sup>	$T_A=25^\circ C$	$P_D$	3.1	1.7	W
	$T_A=70^\circ C$		2.0	1.1	
Junction and Storage Temperature Range		$T_J, T_{STG}$		-55 to 150	°C

## Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup>	$t \leq 10s$	$R_{\theta JA}$	31	40	°C/W
Maximum Junction-to-Ambient <sup>A</sup>	Steady State		59	75	°C/W
Maximum Junction-to-Lead <sup>C</sup>	Steady State	$R_{\theta JL}$	16	24	°C/W

Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D = -250\mu\text{A}$ , $V_{GS} = 0\text{V}$	-40			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS} = -40\text{V}$ , $V_{GS} = 0\text{V}$ $T_J = 55^\circ\text{C}$		-1		$\mu\text{A}$
				-5		
$I_{\text{GSS}}$	Gate-Body leakage current	$V_{DS} = 0\text{V}$ , $V_{GS} = \pm 20\text{V}$			$\pm 100$	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = -250\mu\text{A}$	-1	-1.5	-2.5	V
$I_{D(\text{ON})}$	On state drain current	$V_{GS} = -10\text{V}$ , $V_{DS} = -5\text{V}$	-120			A
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS} = -10\text{V}$ , $I_D = -10\text{A}$ $V_{GS} = -4.5\text{V}$ , $I_D = -8\text{A}$		12.5	15	$\text{m}\Omega$
				16	20	
$g_{FS}$	Forward Transconductance	$V_{DS} = -5\text{V}$ , $I_D = -10\text{A}$		25		S
$V_{SD}$	Diode Forward Voltage	$I_S = -1\text{A}$ , $V_{GS} = 0\text{V}$		-0.7	-1	V
$I_S$	Maximum Body-Diode Continuous Current				-3	A
<b>DYNAMIC PARAMETERS</b>						
$C_{iss}$	Input Capacitance	$V_{GS}=0\text{V}$ , $V_{DS}=-20\text{V}$ , $f=1\text{MHz}$		2500	3000	pF
$C_{oss}$	Output Capacitance			260		pF
$C_{rss}$	Reverse Transfer Capacitance			180		pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}$ , $V_{DS}=0\text{V}$ , $f=1\text{MHz}$	2.5	4	6	$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=-10\text{V}$ , $V_{DS}=-20\text{V}$ , $I_D=-10\text{A}$		42	55	nC
$Q_g(4.5\text{V})$	Total Gate Charge			18.6		nC
$Q_{gs}$	Gate Source Charge			7		nC
$Q_{gd}$	Gate Drain Charge			8.6		nC
$t_{D(\text{on})}$	Turn-On Delay Time	$V_{GS}=-10\text{V}$ , $V_{DS}=-20\text{V}$ , $R_L = 2\Omega$ , $R_{GEN} = 3\Omega$		9.4		ns
$t_r$	Turn-On Rise Time			20		ns
$t_{D(\text{off})}$	Turn-Off Delay Time			55		ns
$t_f$	Turn-Off Fall Time			30		ns
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=-10\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$		38	49	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge	$I_F=-10\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$		47		nC

A: The value of  $R_{\thetaJA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C. The  $R_{\thetaJA}$  is the sum of the thermal impedance from junction to lead  $R_{\thetaJL}$  and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using  $t \leq 300\mu\text{s}$  pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ . The SOA curve provides a single pulse rating.

F. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.

G.  $E_{AR}$  and  $I_{AR}$  ratings are based on low frequency and duty cycles to keep  $T_J=25\text{C}$ .

### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

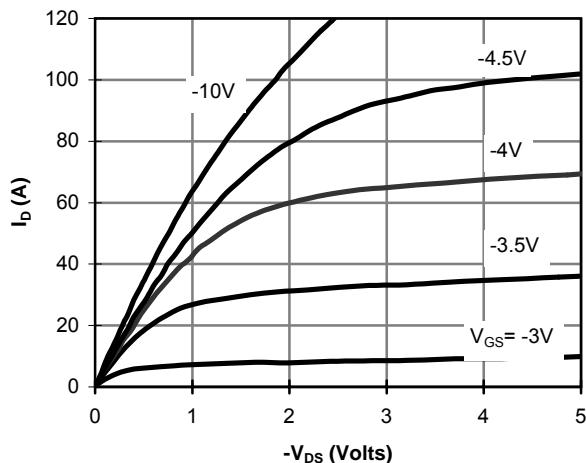


Figure 1: On-Region Characteristics

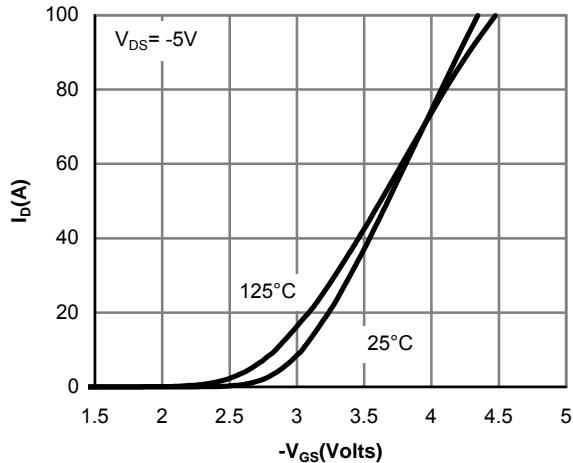


Figure 2: Transfer Characteristics

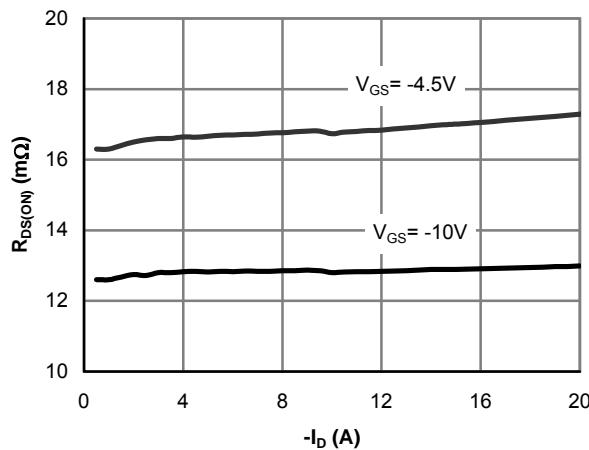


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

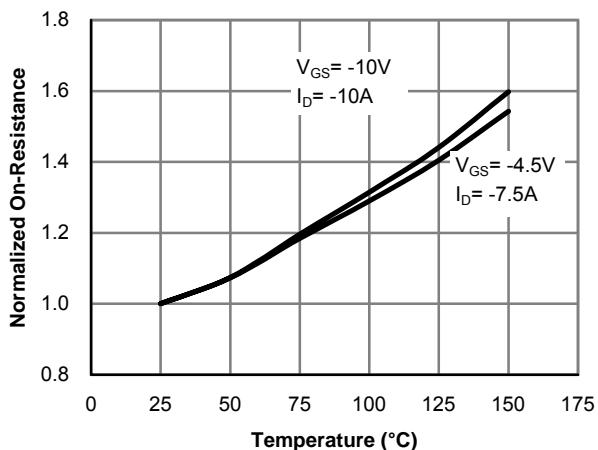


Figure 4: On-Resistance vs. Junction Temperature

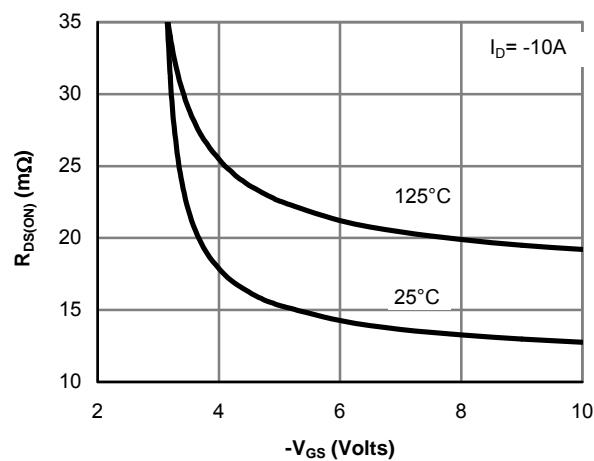


Figure 5: On-Resistance vs. Gate-Source Voltage

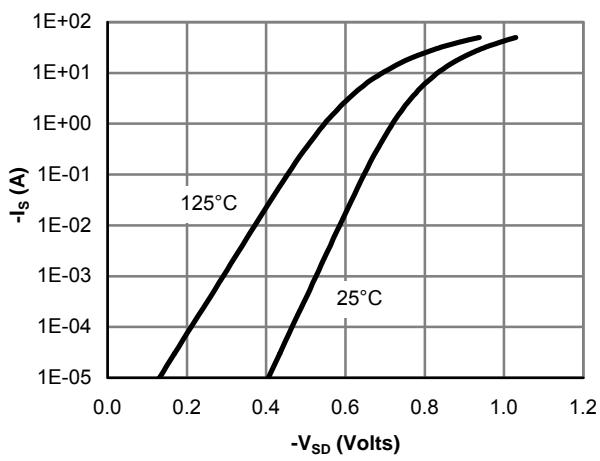


Figure 6: Body-Diode Characteristics

### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

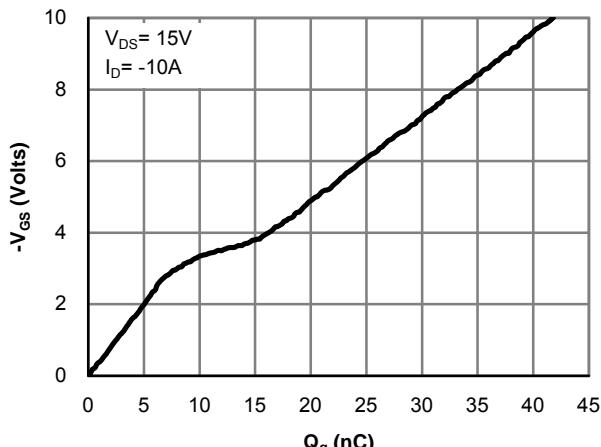


Figure 7: Gate-Charge Characteristics

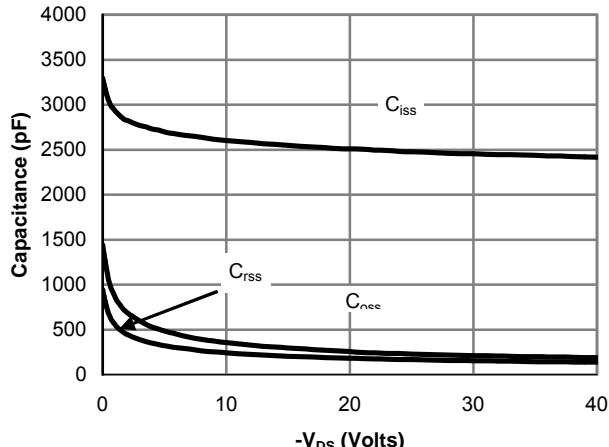


Figure 8: Capacitance Characteristics

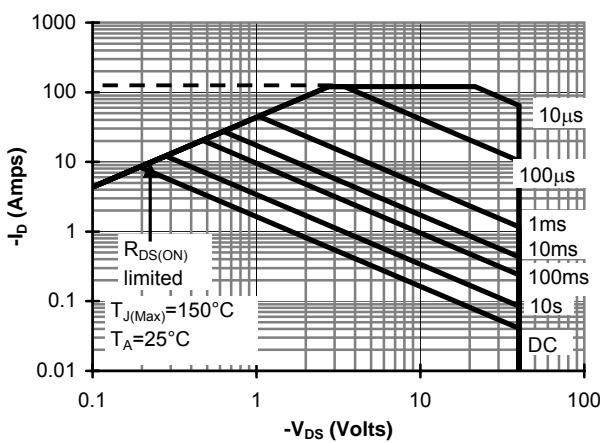


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

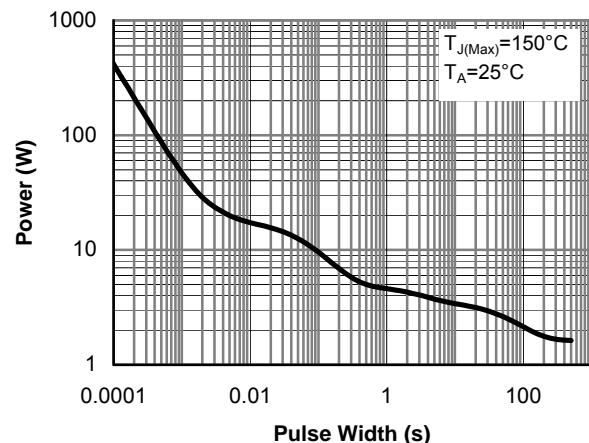


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

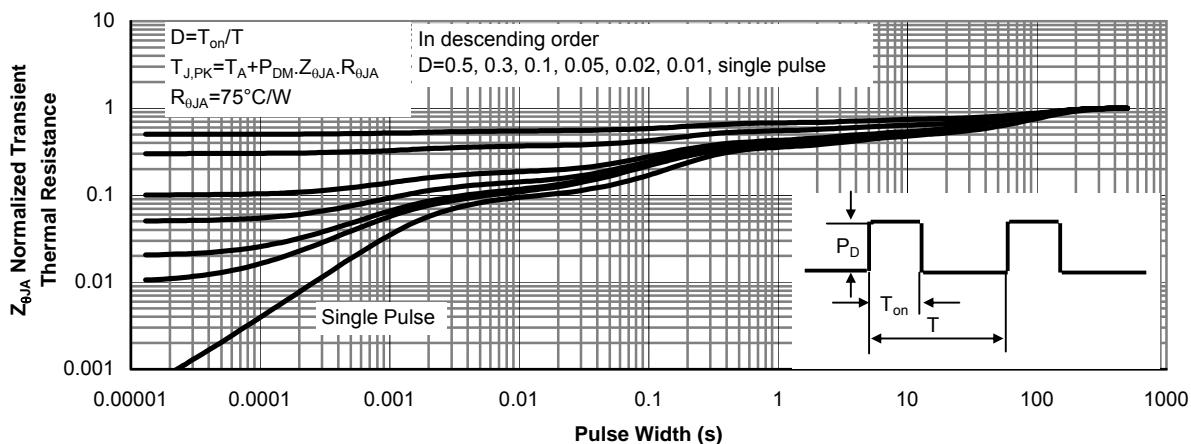
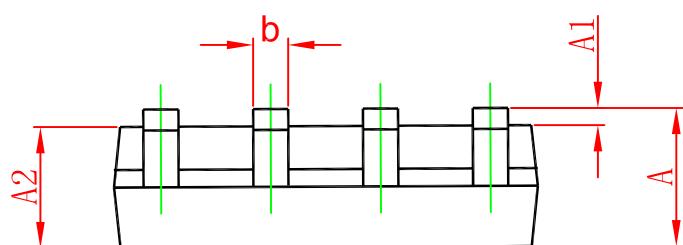
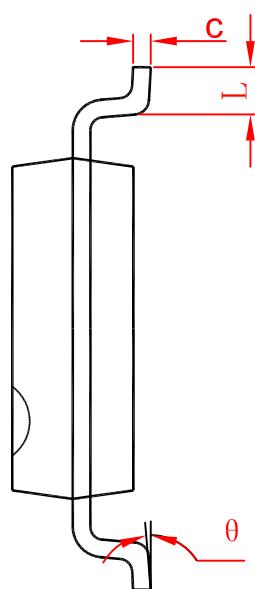
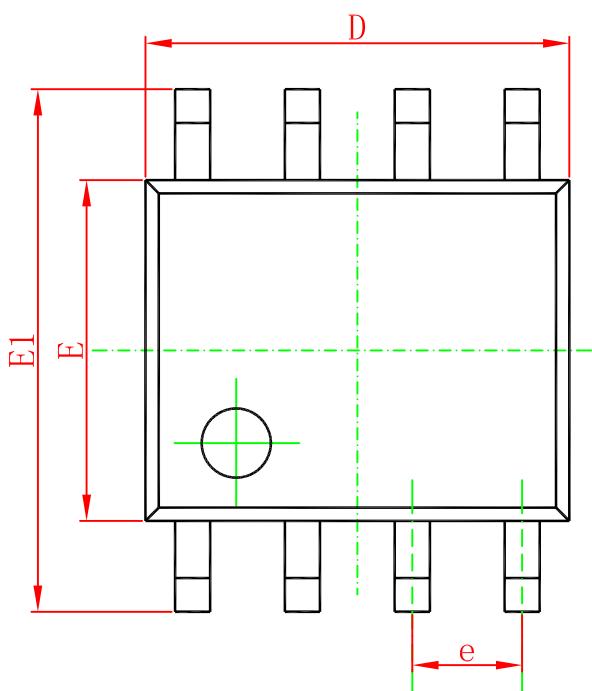


Figure 11: Normalized Maximum Transient Thermal Impedance (Note E)

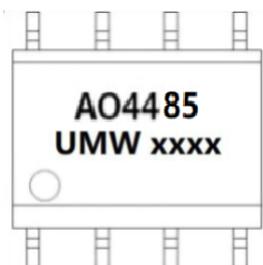
## PACKAGE OUTLINE DIMENSIONS

SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

## Marking



("xxxx"代表年份周期)

## Ordering information

Order code	Package	Baseqty	Deliverymode
UMW AO4485	SOP-8	3000	Tape and reel